

Serial No. 10/050,384

In the Claims:

1. (Currently Amended) A method of manufacturing a structural frame for dissipating heat from an electronic device, comprising:

providing a base polymer matrix;

mixing a thermally conductive filler material into said base polymer matrix to form molding material having a uniform distribution said filler material throughout said entire molding material;

net-shape injection molding said molding material into a structural frame for supporting electronic components;

providing an electronic circuit board, said electronic circuit board having a heat generating electronic component disposed thereon; and

mounting said electronic circuit board to said structural frame with said electronic component being in physical contact with said structural frame, said electronic component thereby residing in thermal communication with said structural frame;

dissipating heat from said heat generating electronic component through said structural frame.

2. (Original) The method of manufacturing a structural frame of Claim 1, wherein said base polymer matrix is liquid crystal polymer.

3. (Original) The method of manufacturing a structural frame of Claim 1, wherein said thermally conductive filler material is selected from the group consisting of carbon fiber, metallic flakes, boron nitride and mixtures thereof.